

preliminary

Туре	Ag <sup>*</sup> Aİ <sup>*</sup>	V <sub>DRM</sub> / V <sub>RRM</sub>	V <sub>DSM</sub> / V <sub>RSM</sub> [V]	<i>I<sub>T(AV)</sub></i> [A]	Chip Size [mm] x [mm]	Package Options	• <del> </del>
CWP 16-	12 🗸	1200	1300	27	6.50 6.50	sawn on foil vunsawn wafer vin waffle pack v	
	*Frontside options					*Please contact IXYS chip sales	

## **Mechanical Parameters**

Area active Area total Wafer size Ø Thickness Material Max. possible chips per wafer Passivation front side Metallization top side top side Recom. wire bonds (AI) Number / Ø [µm] Metallization backside Reject Ink Dot Size Recom. Storage Environment sawn on foil unsawn wafer in waffle pack

0.15 cm<sup>2</sup>
0.42 cm<sup>2</sup>
150 mm
380 µm
Si
342
Glassivation

solderable: Ti / Ni / Ag \* bondable: Al

5 / 380 1 / 380 solderable (only): Ti / Ni / Ag \*

Cathode

Ø 0.4-1.0 mm

Gate

in org. container, in dry nitrogen < 6 month in org. container, in dry nitrogen < 2 year in org. container, in dry nitrogen < 2 year  $T_{\rm stq} \hspace{1cm} \text{-40} \dots \hspace{1cm} \text{40} \hspace{1cm} \text{°C}$ 

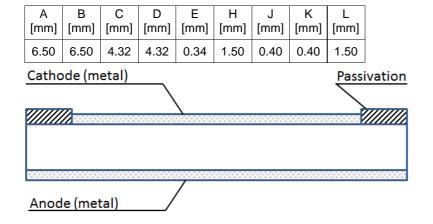
### **Features**

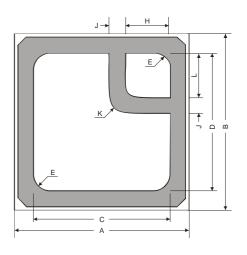
- planar passivated with guardring and channelstopper
- Planar front and back surface
- Non-structured anode contact on full area bottom side

### **Applications**

- DC motor control
- AC power control
- Softstart AC motor controller
- Light, heat and temperature control

# **Dimensions**





<sup>\*</sup>Sinterable top/bottom side on request

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	Ratings				
Symbol	Conditions	min.	typ.	max.	
I <sub>R</sub>	$V_D = Vr = Vrr$	$T_{vJ} = 25^{\circ}C$		0.05	m/
		$T_{VJ} = 150^{\circ}C$		8	m/
$V_{\tau}$	$I_{T} = 45 \text{ A}$	$T_{vJ} = 25 ^{\circ}\text{C}$	1	1.40	'
		T <sub>v,i</sub> = 150 °C		1.45	١
$V_{\tau o}$	For power-loss	s calculations only		0.9	١
<b>r</b> <sub>7</sub>	T <sub>vJ</sub> = 150 °C			12.00	m۵
V <sub>G7</sub>	$V_D = 6 V$	$T_{VJ} = 25^{\circ}C$	10	1.5	١
		$T_{VJ} = -40$ °C		1.6	١
I <sub>GT</sub>	$V_D = 6 V$	$T_{VJ} = 25^{\circ}C$		42	m/
		$T_{VJ} = -40$ °C		80	m/
$V_{GD}$	$T_{VJ} = 150 ^{\circ}\text{C}$	$V = \frac{2}{3} V_{DRM}$		0.2	١
I <sub>GD</sub>				3	m/
I <u>L</u>	t <sub>p</sub> =10 μs	$T_{VJ} = 25^{\circ}C$ $I_{G} = 0.3 \text{ A} \text{ di}_{G}/\text{dt} = 0.3 \text{ A/}\mu\text{s}$		150	m/
I <sub>H</sub>	R <sub>GK</sub> = ∞	$T_{VJ} = 25^{\circ}C$ $V_{D} = 6 \text{ V}$		100	m/
t <sub>gd</sub>	$V_D = \frac{1}{2} V_{DRM}$	$T_{VI} = 25$ °C		2	μ:
		$di_{G}/dt = 0.5 A/\mu$			
t <sub>q</sub>		$I_{T} = 27 \text{ A}$ -di/dt = 10 A/ $\mu$ s		200	μ
	**	$dv/dt = 20 V/\mu s V_D = \frac{2}{3} V drm T_{V,I} = 125 °C$			•
(di/dt) <sub>cr</sub>	repetitive	$I_T = 40$ A		100	A/µs
	non repetitive	I <sub>T</sub> = 27 A		500	A/µs
	$V = \frac{2}{3} V_{DRM}$	$T_{VJ} = 150 ^{\circ}\text{C}$ $di_{G}/dt = 0.3 \text{A/}\mu\text{s}$			
	$I_G = 0.3 A$	$t_p = 200 \ \mu s$ $f = 50 \ Hz$			
(dv/dt) <sub>c</sub> ,	T <sub>VJ</sub> = 150 °C	$V_{DR} = \frac{2}{3} V_{DRM}$		1000	V/µs
	R <sub>GK</sub> = ∞	method 1 (linear voltage rise)			
P <sub>GM</sub>	T <sub>VJ</sub> = 150 °C	$t_p = 30  \mu s$		10	V
		$t_p = 3E \mu s$		5	W
$P_{GAV}$				0.5	V
V <sub>RGM</sub>				10	\
T <sub>VJ</sub>		-40		150	°C
I <sub>T(AV)</sub>	$T_{\rm C} = 100 {\rm ^{\circ}C}$	180° rect.		27	P
	T <sub>VJ</sub> = 150 °C	180° sine		25	P
I <sub>TSM</sub> *	$T_{VJ} = 45^{\circ}C$	t = 10 ms (50) Hz, sine		400	A
	$V_R = 0 V$	t = 8.3 ms (60) Hz, sine		430	P
	T <sub>vJ</sub> = 150 °C	t = 10 ms (50) Hz, sine		360	P
	$V_R = 0 V$	t = 8.3 ms (60) Hz, sine		380	P
l²t *		t = 10 ms (50) Hz, sine		800	Α :
	$V_R = 0 V$	t = 8.3 ms (60) Hz, sine		767	Α :
	T <sub>vJ</sub> = 150 °C	t = 10 ms (50) Hz, sine		648	As
	$V_R = 0 V$	t = 8.3 ms (60) Hz, sine		599	As
R <sub>thJC</sub> *	DC current		1.2		K/W

<sup>\*</sup> Data according to assembled product MMO 36

Data according to IEC 60747

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- the conclusion of quality agreements;
- to establish joint measures to ensure application specific product capabilities and notify that IXYS may delivery dependent on the realization of any such measures.